10-22-1999

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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

MD 10-22-99

1. Name of conveying party(ies):

a) Sukhvinder Kang g) ____
b) Howard V. Mahaney, Jr. h) ____
c) Roger R. Schmidt i) ____
d) Prabjit Singh j) ____
e) ____ k) ____
f) ____ l) ____

More names attached? ___Y x N

2. Name and address of receiving party(ies):

Name: INTERNATIONAL BUSINESS MACHINES CORPORATION
Address: New Orchard Road
Armonk, NY 10504

More names attached? ___Y x N

3. Nature of Conveyance: x Assignment

4. Application number: Filed:
Filed with new application: X yes ___ no

Execution date(s):

a) 10 7 99 g) ____
b) 10 5 99 h) ____
c) 10 11 99 i) ____
d) 10 1 99 j) ____
e) ____ k) ____
f) ____ l) ____

Additional numbers attached? ___Y x N

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Floyd A. Gonzalez
IBM Corporation
Intellectual Property Law
522 South Road, M/S P386
Poughkeepsie NY 12601-5400

6. Total # of applications and patents involved: 01

7. Total fee (37 CFR 3.41): $ 40.00 .

8. Charge to Deposit Account 09-0463. A duplicate copy is enclosed.

DO NOT USE THIS SPACE

9. Statement and Signature: To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Susan L. Nelson

Susan L. Nelson
Signature

10/12/99
Date

Total number of pages including cover sheet, attachments, and document: 4

10/21/1999 DNGUYEN 00000238 090463 09415740

01 FC:581 40.00 CH

Express Mail Label No. (if applicable): EJ896405783US Docket No.: PO9-99-087

ASSIGNMENT

Whereas, we

(1) Sukhvinder Kang of Rochester
County of Oldsted and State of Minnesota

(2) Howard Victor Mahaney, Jr. of Cedar Park
County of Williamson and State of Texas

(3) Roger R. Schmidt of Poughkeepsie
County of Dutchess and State of New York
And
(4) Prabjit Singh of Poughkeepsie
County of Dutchess and State of New York

have invented certain improvements in HEATED PCB INTERCONNECT FOR COOLED IC CHIP MODULES

and executed a United States Patent Application therefor on

(1) ____________________, (2) ____________________

(3) [illegible] 11 99, and (4) 10 11 99

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York, 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patents granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

(1) at
on ____________________ ____________________
Sukhvinder Kang

(2) at
on ____________________ ____________________
Howard Victor Mahaney, Jr.

(3) at Poughkeepsie, NY
on 10/11/99 Roger R Schmidt
Roger R. Schmidt

(4) at Poughkeepsie, NY
on 10/11/99
Prabjit Singh

IBM Docket No: PO9-99-087

ASSIGNMENT

Whereas, we

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County of Olmsted and State of Minnesota

(2) Howard Victor Mahaney, Jr. of Cedar Park
County of Williamson and State of Texas

(3) Roger R. Schmidt of Poughkeepsie
County of Dutchess and State New York

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and executed a United States Patent Application therefor on

(1)__________, (2) 10/8/99 (3)__________.

(4)__________

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Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and the invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

(1) at
on __________ __________
Sukhvinder Kang

(2) at Austin TX
on 10/8/99 Howard Victor Mahaney Jr.
Howard Victor Mahaney, Jr.

(3) at Poughkeepsie, NY
on __________ __________
Roger R. Schmidt

(4) at Poughkeepsie, NY
on __________ __________
Prabjit Singh

IBM Docket No: P09-99-087

ASSIGNMENT

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County of Olmsted and State of Minnesota

(2) Howard Victor Mahaney, Jr. of Cedar Park
County of Williamson and State of Texas

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(1) 10/7/99 , (2) ____________ (3) ____________

(4) ____________

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Signed

(1) at Rochester, MN
on 10/7/99
S Kang. Sukhvinder Kang.
Sukhvinder Kang

(2) at
on ____________
____
Howard Victor Mahaney, Jr.

(3) at Poughkeepsie, NY
on ____________
____
Roger R. Schmidt

(4) at Poughkeepsie, NY
on ____________
____
Prabjit Singh